

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (original): A supporting device for an integrated circuit package having a column grid array interconnection with a printed circuit board, said supporting device comprising:

a shim that is inserted between the integrated circuit package and the printed circuit board,

wherein said shim is mechanically and removably fastened to the printed circuit board.

Claim 2 (original): The supporting device of claim 1, wherein the shim comprises an extrusion that is inserted between the integrated circuit package and the printed circuit board, and a base that comprises a fastening means to secure the shim to the printed circuit board.

Claim 3 (currently amended): The supporting device of claim ~~1~~2, wherein the base and the extrusion are shaped to prevent the extrusion from coming into contact with a solder column of the integrated circuit package.

Claim 4 (original): The supporting device of claim 3, wherein the extrusion is designed to provide a gap between the extrusion and the integrated circuit package immediately after the installation of the supporting device.

Claim 5 (original): The supporting device of claim 1, wherein the supporting device is installed on a corner of the integrated circuit package.

Claim 6 (original): The supporting device of claim 5, wherein the supporting device has a Y shape.

Claim 7 (original): The supporting device of claim 1, wherein the supporting device is made of a material having a coefficient of thermal expansion that matches coefficients of thermal expansion of solder columns of the integrated circuit package.

Claim 8 (currently amended): The supporting device of claim 2, wherein the ~~fastening~~fastening means is a screw.

Claim 9 (currently amended): The supporting device of claim 2, wherein the ~~fastening~~fastening means is a dimple.

Claim 10 (currently amended): A method for mechanically supporting an integrated circuit package having a column grid array interconnection with a printed circuit board, said method comprising the steps of:

inserting one or more supporting devices between the integrated circuit package and the printed circuit board; and

mechanically and removably fastening the one or more supporting devices to the printed circuit board.

Claim 11 (currently amended): The method of claim 10, wherein the inserting step inserts one or more supporting devices between the integrated circuit package and the printed circuit board after the integrated circuit package is solder attached to the printed circuit board.

Claim 12 (currently amended): The method of claim 11, wherein the inserting step positions the one or more supporting devices so that there is a gap between a top surface of the one or more supporting devices and an under surface of the integrated circuit package.

Claim 13 (currently amended): The method of claim 10, wherein the fastening step fastens the one or more supporting devices on one or more corners of the integrated circuit package.

Claim 14 (currently amended): The method of claim 10, wherein the fastening step fastens the one or more supporting devices to the printed circuit board by screws.

Claim 15 (currently amended): The method of claim 10, wherein the fastening step fastens the one or more supporting devices to the printed circuit board by dimples.